Configurable Multifunction Gate

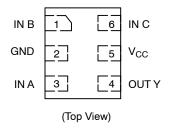
The NLX1G98 MiniGate $^{\text{M}}$ is an advanced high-speed CMOS multifunction gate. The device allows the user to choose logic functions MUX, AND, OR, NAND, NOR, INVERT and BUFFER. The device has Schmitt-trigger inputs, thereby enhancing noise immunity.

The NLX1G98 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

Features

- High Speed: $t_{PD} = 3.4 \text{ ns (Typ)} @ V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1 \mu A$ (Maximum) at $T_A = 25^{\circ}C$
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb-Free Devices

PIN ASSIGNMENTS





ON Semiconductor®

http://onsemi.com

MARKING DIAGRAMS



ULLGA6 1.0 x 1.0 CASE 613AD





ULLGA6 1.2 x 1.0 CASE 613AE





ULLGA6 1.45 x 1.0 CASE 613AF





UDFN6 1.0 x 1.0 CASE 517BX





UDFN6 1.2 x 1.0 CASE 517AA





UDFN6 1.45 x 1.0 CASE 517AQ



A = Specific Device Code M = Date Code

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

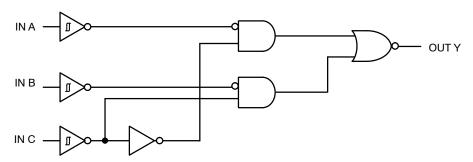


Figure 1. Function Diagram

PIN ASSIGNMENT

1	IN B
2	GND
3	IN A
4	OUT Y
5	V _{CC}
6	IN C

FUNCTION TABLE*

	Input			
Α	В	С	Υ	
L	L	L	Н	
L	L	Н	Н	
L	Н	L	L	
L	Н	Н	Н	
Н	L	L	Н	
Н	L	Н	L	
Н	Н	L	L	
Н	Н	Н	L	

^{*}To select a logic function, please refer to "Logic Configurations section".

LOGIC CONFIGURATIONS

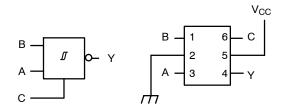


Figure 2. 2-Input MUX with Output Inverted

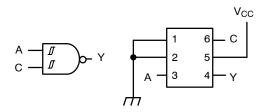


Figure 3. 2-Input NAND (When B = "L")

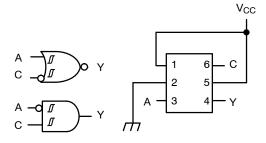


Figure 4. 2-Input NOR with Input C Inverted (When B = "H")

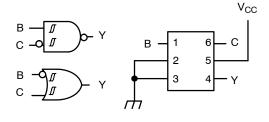


Figure 5. 2-Input NAND with Input C Inverted (When A = "L")

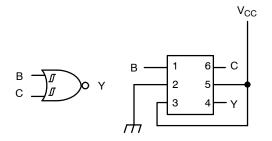


Figure 6. 2-Input NOR (When A ="H")

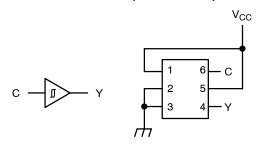


Figure 7. Buffer (When A = "L" and B = "H")

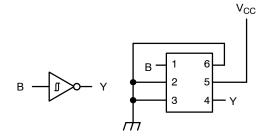


Figure 8. Inverter (When A = C = "L")

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{CC}	DC Supply Voltage	−0.5 to +7.0	V	
V _{IN}	DC Input Voltage		−0.5 to +7.0	V
V _{OUT}	DC Output Voltage		-0.5 to +7.0	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < GND	-50	mA
ΙO	DC Output Source/Sink Current		±50	mA
I _{CC}	DC Supply Current Per Supply Pin		± 100	mA
I _{GND}	DC Ground Current per Ground Pin		± 100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature Under Bias		150	°C
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating Oxygen	ndex: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage Human Body M Machine M Charged Device M	/lodel (Note 3)	>2000 >200 N/A	V
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below GND at 125	°C (Note 5)	±500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm@by@1 inch, 2 ounce copper trace no air flow.

- Tested to EIA/JESD22-A114-A.
 Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	1	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage		1.65	5.5	V
V _{IN}	Digital Input Voltage		0	5.5	V
V _{OUT}	Output Voltage		0	5.5	V
T _A	Operating Free-Air Temperature		-55	+125	°C
Δt/ΔV	$V_{CC} = 3$	5 V ± 0.2 V 3 V ± 0.3 V 0 V ± 0.5 V	0 0 0	No Limit No Limit No Limit	nS/V

DC ELECTRICAL CHARACTERISTICS

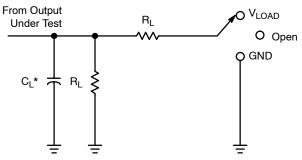
			V _{CC}	-	Γ _A = 25°		T _A ≤	+85°C		55°C to 5°C	
Symbol	Parameter	Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V_{T+}	Positive		1.65	0.79		1.16		1.16		1.16	V
	Threshold Voltage		2.3	1.11		1.56		1.56		1.56	
			3.0	1.5		1.87		1.87		1.87	
			4.5	2.16		2.74		2.74		2.74	
			5.5	2.61		3.33		3.33		3.33	
V_{T-}	Negative		1.65	0.35		0.62	0.35		0.35		V
	Threshold Voltage		2.3	0.58		0.87	0.58		0.58		
	voltage		3.0	0.84		1.19	0.84		0.84		
			4.5	1.41		1.9	1.41		1.41		
			5.5	1.78		2.29	1.78		1.78		
V _H	Hysteresis		1.65	0.30		0.62	0.30	0.62	0.30	0.62	V
	Voltage		2.3	0.40		0.8	0.40	0.8	0.40	0.8	
			3.0	0.53		0.87	0.53	0.87	0.53	0.87	
			4.5	0.71		1.04	0.71	1.04	0.71	1.04	
			5.5	0.8		1.2	0.8	1.2	0.8	1.2	
V _{OH}	Minimum High-Level	$V_{IN} = V_{T-MIN} \text{ or } V_{T+MAX}$ $I_{OH} = -50 \mu\text{A}$	1.65 – 5.5	V _{CC} - 0.1			V _{CC} - 0.1		V _{CC} - 0.1		V
	Output Voltage	$V_{IN} = V_{T-MIN}$ or V_{T+MAX}									
		I _{OH} = -4 mA	1.65	1.2			1.2		1.2		
		I _{OH} = -8 mA	2.3	1.9			1.9		1.9		
		I _{OH} = -16 mA	3.0	2.4			2.4		2.4		
		I _{OH} = -24 mA	3.0	2.3			2.3		2.3		
		I _{OH} = -32 mA	4.5	3.8			3.8		3.8		
V _{OL}	Maximum Low-Level	$V_{IN} = V_{T-MIN}$ or V_{T+MAX} $I_{OL} = 50 \mu A$	1.65 – 5.5			0.1		0.1		0.1	V
	Output Voltage	$V_{IN} = V_{T-MIN}$ or V_{T+MAX}									
		I _{OL} = 4 mA	1.65			0.45		0.45		0.45	
		I _{OL} = 8 mA	2.3			0.3		0.3		0.3	
		I _{OL} = 16 mA	3.0			0.4		0.4		0.4	
		I _{OL} = 24 mA	3.0			0.55		0.55		0.55	1
		I _{OL} = 32 mA	4.5			0.55		0.55		0.55	1
I _{IN}	Input Leakage Current	0 ≤ V _{IN} ≤ 5.5 V	0 to 5.5			±0.1		±1.0		±1.0	μΑ
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND	5.5			1.0		10		10	μΑ

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ ns}$)

				7	Γ _A = 25°(T _A ≤	+85°C		-55°C 25°C	
Symbol	Parameter	V _{CC} (V)	Test Condition	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} ,	Propagation Delay,	1.65 – 1.95		3.2	8.9	14.4	3.2	14.4	3.2	14.4	ns
t _{PHL}	Any Input to Output Y (See Test Circuit)	2.3 – 2.7		2.0	5.2	8.3	2.0	9.0	2.0	9.3	
		3.0 – 3.6		1.5	4.0	7.2	1.5	7.5	1.5	7.8	
		4.5 – 5.5		1.1	3.4	5.8	1.1	6.1	1.1	6.5	
C _{IN}	Input Capacitance				3.5						pF
C _{PD}	Power Dissipation Capacitance (Note 6)	5.0	f = 10 MHz		22						pF

^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption: $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$.

TEST CIRCUIT AND VOLTAGE WAVEFORMS



S1
Open
V_{LOAD}
GND

Figure 9. Load Circuit

	Inputs						
V _{CC}	VI	t _r /t _f	V_{M}	V_{LOAD}	C _L	R_{L}	V_Δ
1.8 V ± 0.15 V	V _{CC}	≤ 2 ns	V _{CC} /2	$2 \times V_{CC}$	30 pF	1 kΩ	0.15 V
2.5 V ± 0.2 V	V _{CC}	≤ 2 ns	V _{CC} /2	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
3.3 V ± 0.3 V	3 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5.5 V ± 0.5 V	V _{CC}	≤ 2.5 ns	V _{CC} /2	2 x V _{CC}	50 pF	500 Ω	0.3 V

^{*}C_L includes probes and jig capacitance.

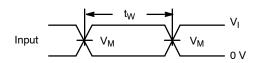


Figure 10. Voltage Waveforms Pulse Duration

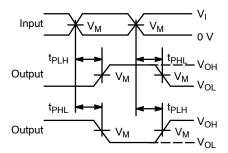


Figure 12. Voltage Waveforms Propagation Delay Times Inverting and Noninverting Outputs

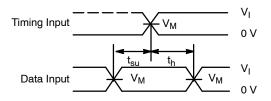


Figure 11. Voltage Waveforms Setup and Hold Times

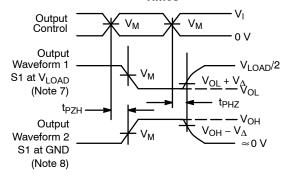


Figure 13. Voltage Waveforms Enable and Disable Times Low- and High-Level Enabling

- 7. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control.
- 8. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control
- 9. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_0 = 50 \Omega$.
- 10. The outputs are measured one at a time, with one transition per measurement.
- 11. All parameters are waveforms are not applicable to all devices.

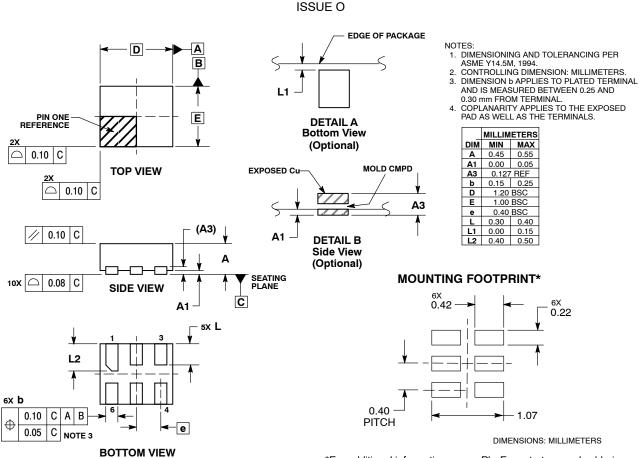
ORDERING INFORMATION

Device	Package	Shipping [†]
NLX1G98AMX1TCG	ULLGA6 – 0.5P (Pb-Free)	3000 / Tape & Reel
NLX1G98BMX1TCG	ULLGA6 - 0.4P (Pb-Free)	3000 / Tape & Reel
NLX1G98CMX1TCG	ULLGA6 - 0.35P (Pb-Free)	3000 / Tape & Reel
NLX1G98MUTCG (In Development)	UDFN6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel
NLX1G98AMUTCG (In Development)	UDFN6, 1.45 x 1.0, 0.5P (Pb-Free)	3000 / Tape & Reel
NLX1G98CMUTCG (In Development)	UDFN6, 1.0 x 1.0, 0.35P (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

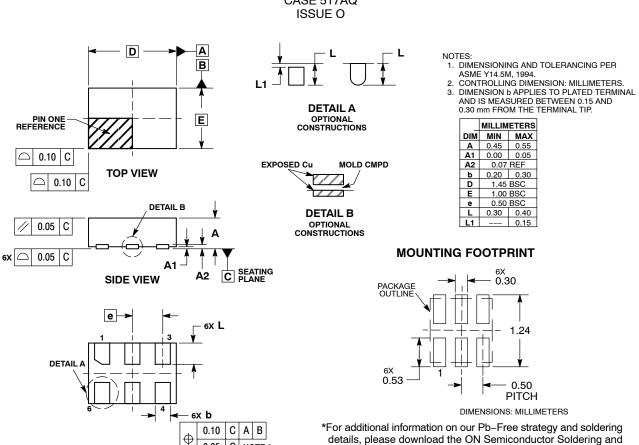
UDFN6 1.2x1.0, 0.4P CASE 517AA ISSUE O



^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

UDFN6 1.45x1.0, 0.5P CASE 517AQ ISSUE O



Mounting Techniques Reference Manual, SOLDERRM/D.

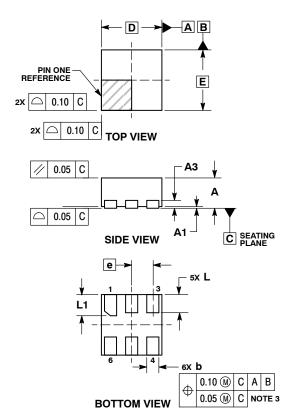
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BOTTOM VIEW

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PACKAGE DIMENSIONS

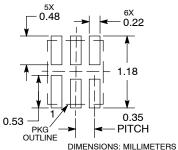
UDFN6 1.0x1.0, 0.35P CASE 517BX ISSUE O



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
 4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETERS					
DIM	MIN	MAX				
Α	0.45	0.55				
A1	0.00	0.05				
А3	0.13 REF					
b	0.12	0.22				
D	1.00	BSC				
E	1.00	BSC				
е	0.35 BSC					
L	0.25	0.35				
L1	0.30	0.40				

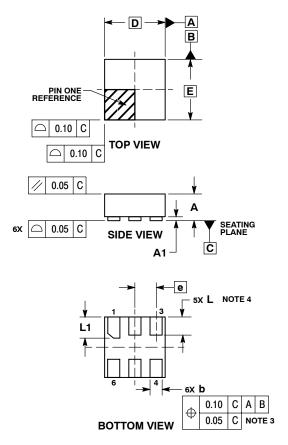
RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

ULLGA6 1.0x1.0, 0.35P CASE 613AD ISSUE A

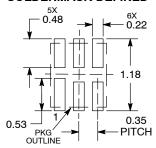


- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
 4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.
- PACKAGE IS ALLOWED.

	MILLIMETERS				
ЫΜ	MIN	MAX			
Α		0.40			
A1	0.00	0.05			
b	0.12	0.22			
D	1.00	BSC			
E	1.00 BSC				
е	0.35 BSC				
L	0.25	0.35			
L1	0.30	0.40			

MOUNTING FOOTPRINT SOLDERMASK DEFINED*

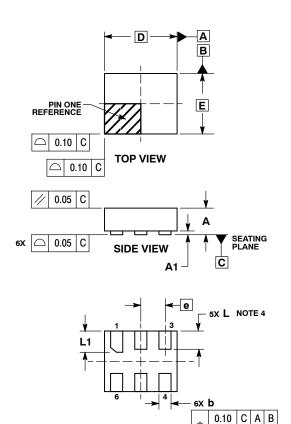


DIMENSIONS: MILLIMETERS

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PACKAGE DIMENSIONS

ULLGA6 1.2x1.0, 0.4P CASE 613AE ISSUE A



BOTTOM VIEW

Ф

0.05 C NOTE 3

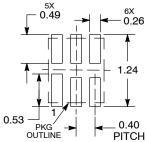
NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
 4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

	MILLIMETERS				
DIM	MIN	MAX			
Α		0.40			
A1	0.00	0.05			
ь	0.15	0.25			
ם	1.20	BSC			
Е	1.00	BSC			
Φ	0.40 BSC				
L	0.25	0.35			
11	0.35	0.45			

MOUNTING FOOTPRINT SOLDERMASK DEFINED*

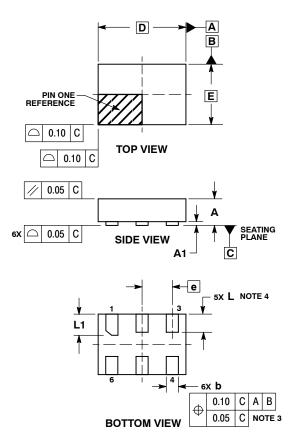


DIMENSIONS: MILLIMETERS

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PACKAGE DIMENSIONS

ULLGA6 1.45x1.0, 0.5P CASE 613AF **ISSUE A**

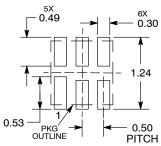


NOTES:

- DIMENSIONING AND TOLERANCING PER
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSION 6 APPLIES TO PLATED TERMINAL AND 1S MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
 A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE
- PACKAGE IS ALLOWED.

	MILLIMETERS	
DIM	MIN	MAX
Α		0.40
A1	0.00	0.05
b	0.15	0.25
D	1.45 BSC	
Е	1.00 BSC	
е	0.50 BSC	
L	0.25	0.35
L1	0.30	0.40

MOUNTING FOOTPRINT SOLDERMASK DEFINED*



DIMENSIONS: MILLIMETERS

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NLVVHC1G14DTT1G NLX2G08DMUTCG NLX2G08MUTCG MC74HCT20ADR2G 091992B 091993X 093560G 634701C 634921A
NL17SG32P5T5G NL17SG86DFT2G NLU1G32CMUTCG NLV14001UBDR2G NLVVHC1G132DTT1G NLVVHC1G86DTT1G
NLX1G11AMUTCG NLX1G97MUTCG 746427X 74AUP1G17FW5-7 74LS38 74LVC1G08Z-7 74LVC32ADTR2G 74LVC1G125FW4-7
74LVC08ADTR2G MC74HCT20ADTR2G NLU1G08CMX1TCG NLV14093BDTR2G NLV17SZ00DFT2G NLV17SZ02DFT2G
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